

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



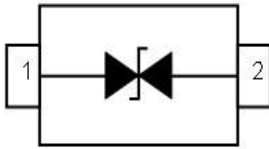
GDT



PLED

Product data sheet

PIN CONFIGURATION



SOD-323

FEATURES

- ◇ IEC61000-4-2 (ESD) ±8kV (Contact), ±15kV (Air)
- ◇ IEC61000-4-4 (EFT) 40A (5/50ns)
- ◇ Peak power dissipation: 60W (8/20µs)
- ◇ Protects one I/O line
- ◇ Low clamping voltage
- ◇ Working voltages : 5V
- ◇ Low leakage current

MACHANICAL DATA

- ◇ SOD-323 package
- ◇ Terminals: Tin plated, solderable per MIL-STD-750, method 2026
- ◇ Packaging: Tape and Reel
- ◇ Reel size: 7 inch

APPLICATIONS

- ◇ High Speed Line :USB1.0/2.0, VGA, DVI, SDI,
- ◇ Serial and Parallel Ports
- ◇ Notebooks, Desktops, Servers
- ◇ Projection TV
- ◇ Cellular handsets and accessories
- ◇ Portable instrumentation
- ◇ Peripherals

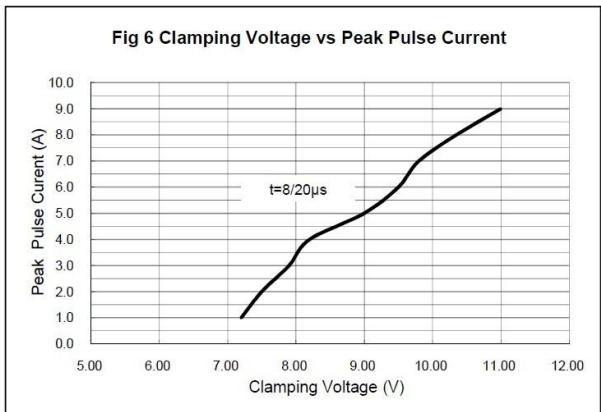
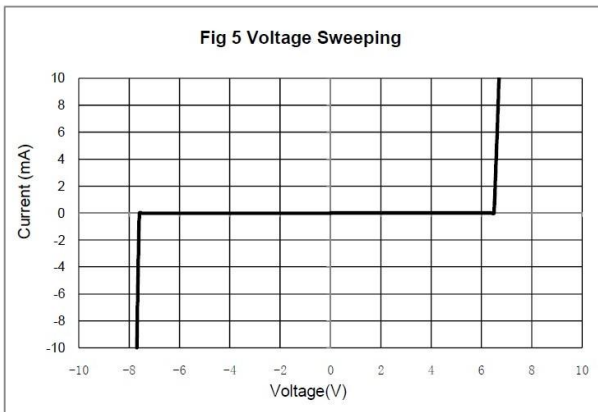
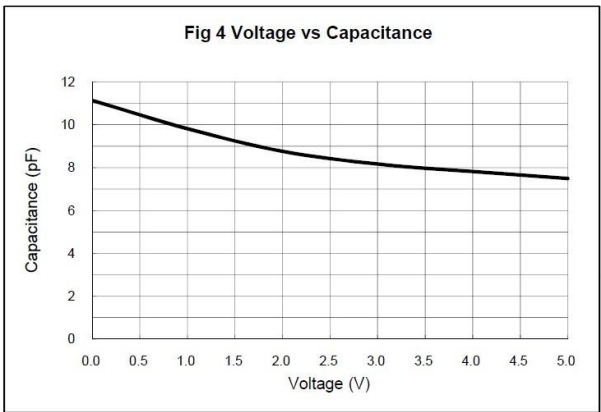
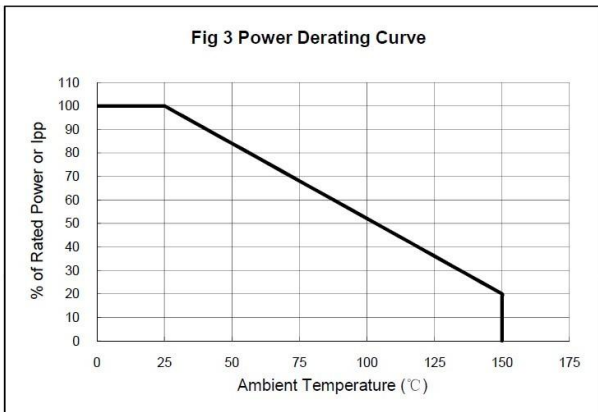
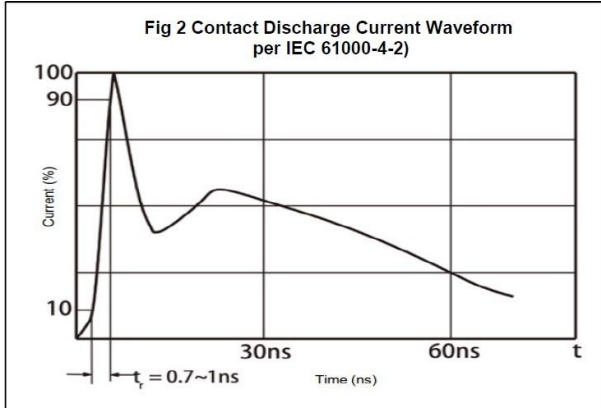
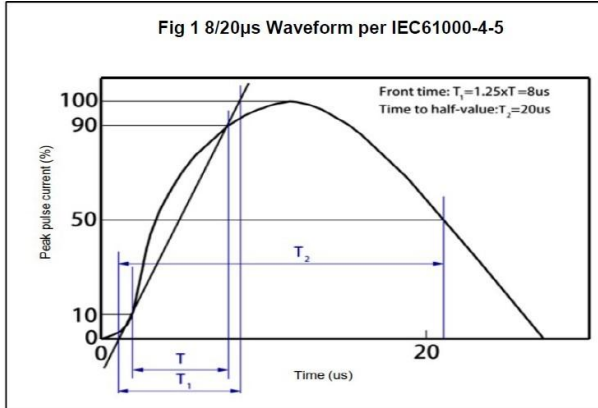
ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units
V _{ESD}	ESD per IEC 61000-4-2 (Contact)	±30	kV
	ESD per IEC 61000-4-2 (Air)	±30	
P _{PP}	Peak Pulse Power (8/20µs)	60	W
T _{OPT}	Operating Temperature	-55~150	°C
T _{STG}	Storage Temperature	-55~150	°C

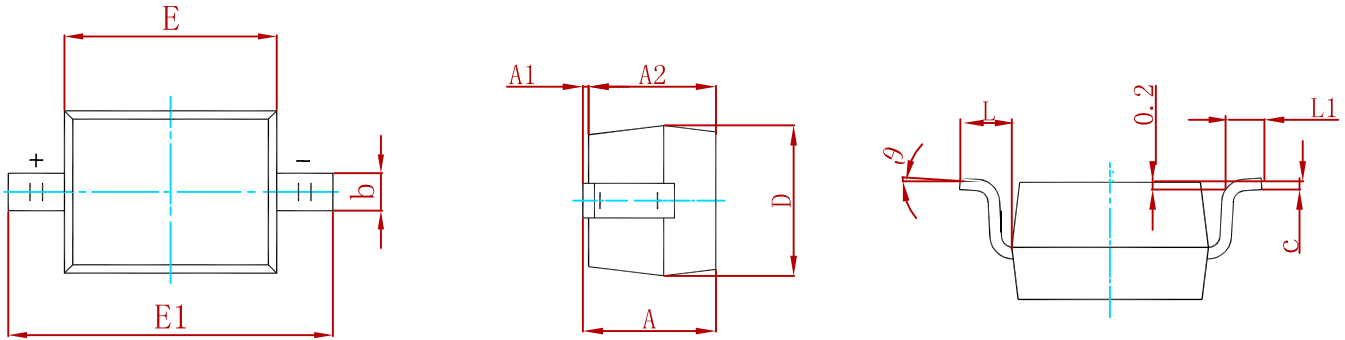
ELECTRICAL CHARACTERISTICS (Tamb=25°C)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
V _{RWM}	Reverse Working Voltage				5.0	V
V _{BR}	Reverse Breakdown Voltage	I _T = 1mA	5.6		7.8	V
I _R	Reverse Leakage Current	V _{RWM} = 5V			1.0	µA
V _C	Clamping Voltage	I _{PP} = 5A, t _p = 8/20µs			12.0	V
C _J	Junction Capacitance	V _R = 0V, f = 1MHz			18	pF

ELECTRICAL CHARACTERISTICS CURVE

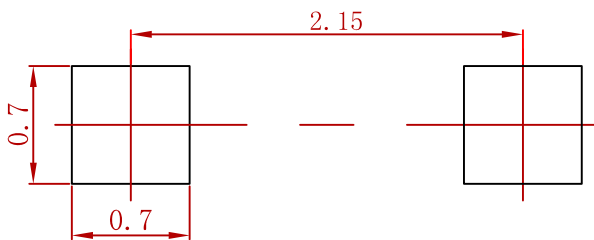


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:**
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD3Z5.0C-MS	SOD-323	3000

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